Measurement condition

Ambient temperature T_A: 23 °C
Input power level: 0 dBm
Terminating impedance: *
Input: 1035 Ω || -7.2 pF
Output: 1007 Ω || -7.2 pF

Characteristics

Remark:
The reference level for the relative attenuation a_{rel} of the TFS70CE is the minimum of the pass band attenuation. This value is defined as the insertion loss a_e. The nominal frequency f_N is fixed at 70 MHz without any tolerance. The values of relative attenuation a_{rel} are guaranteed over the whole operating temperature range. The frequency shift of the filter within the operating temperature range is included in the production tolerance scheme.

D a t a		**typ. value**		**tolerance / limit**		
Insertion loss (reference level)	a_e	10.4	dB	max.	12	dB
Nominal frequency	f_N				70	MHz
Passband	PB	14.8	MHz	f_N ±	6.0	MHz
Pass band ripple within PB		0.4	dB	max.	1.0	dB
Relative attenuation	a_{rel}					
f_N … f_N ± 6	MHz	0.4	dB	max.	1	dB
f_N ± 9.5 MHz … f_N ± 19	MHz	18	dB	min.	15	dB
f_N ± 19 MHz … f_N ± 25	MHz	45	dB	min.	40	dB
f_N + 25 MHz … f_N + 100	MHz	50	dB	min.	45	dB
f_N - 25 MHz … f_N - 50	MHz	55	dB	min.	45	dB
Group delay ripple within PB	GDR	50	ns	max.	150	ns
Return loss within PB		14	dB	min.	10	dB
Input power		-		max	10	dBm
Operating temperature range	OTR			- 40°C ... + 85°C		
Storage temperature range				- 55°C ... + 125°C		
Temperature coefficient of frequency	TC_f **	-94	ppm/K			

*) The terminating impedances depend on parasitics and q-values of matching elements and the board used, and are to be understood as reference values only. Should there be additional questions do not hesitate to ask for an application note or contact our design team.
**) $\Delta f = TC_f(T - T_A)f_N$

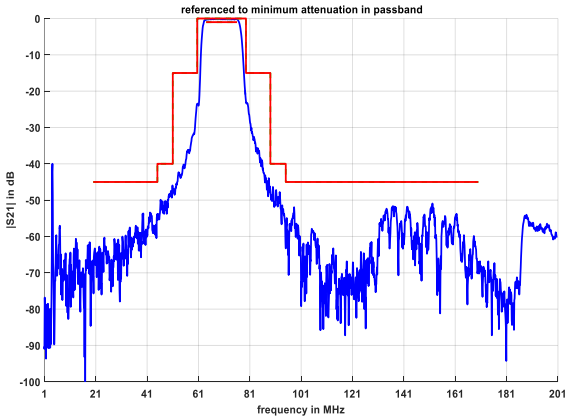
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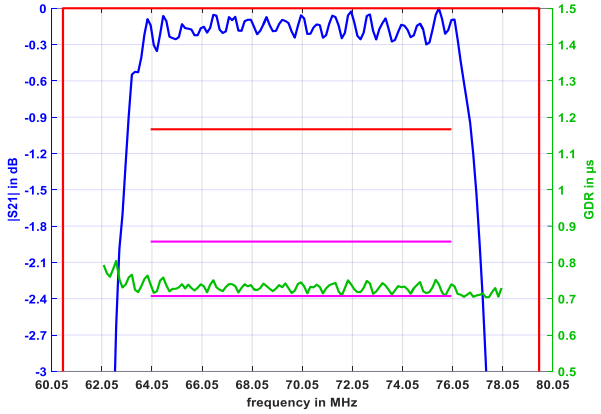
Checked / Approved:

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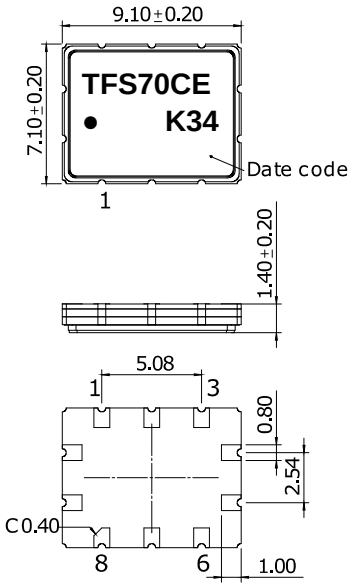
Filter characteristic





Construction and pin connection

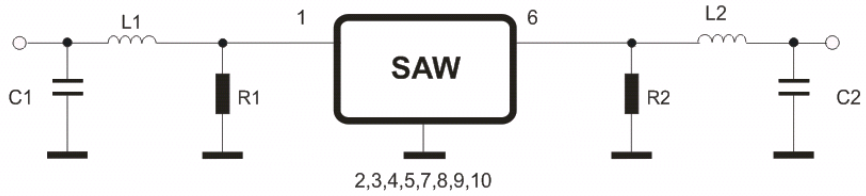
(All dimensions in mm)



1	Input
2	Ground
3	Ground
4	Ground
5	Ground
6	Output
7	Ground
8	Ground
9	Ground
10	Ground

Date code:	Year + week
K	2018
L	2019
M	2020
...	

50 Ω Test circuit



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Stability characteristics, reliability

After the following tests the filter shall meet the whole specification:

1. Shock: 500 g, 1 ms, half sine wave, 3 shocks each plane;
   DIN IEC 60068 T2 - 27

2. Vibration: 10 Hz to 2000 Hz, 0.35 mm or 5 g respectively, 1 octave per min, 10 cycles per plane, 3 planes; DIN IEC 60068 T2 - 6

3. Change of temperature: -55 °C to 125 °C / 15 min. each / 100 cycles
   DIN IEC 60068 part 2 – 14 Test N

4. Resistance to solder heat (reflow): reflow possible: three times max.;
   for temperature conditions refer to the attached "Air reflow temperature conditions" on page 4;

5. SAW devices are Electrostatic Discharge (ESD) sensitive devices.

This filter is RoHS compliant (2011/65/EU)

Packing

Tape & Reel: IEC 286 – 3, with exception of value for N and minimum bending radius;
tape type II, embossed carrier tape with top cover tape on the upper side;

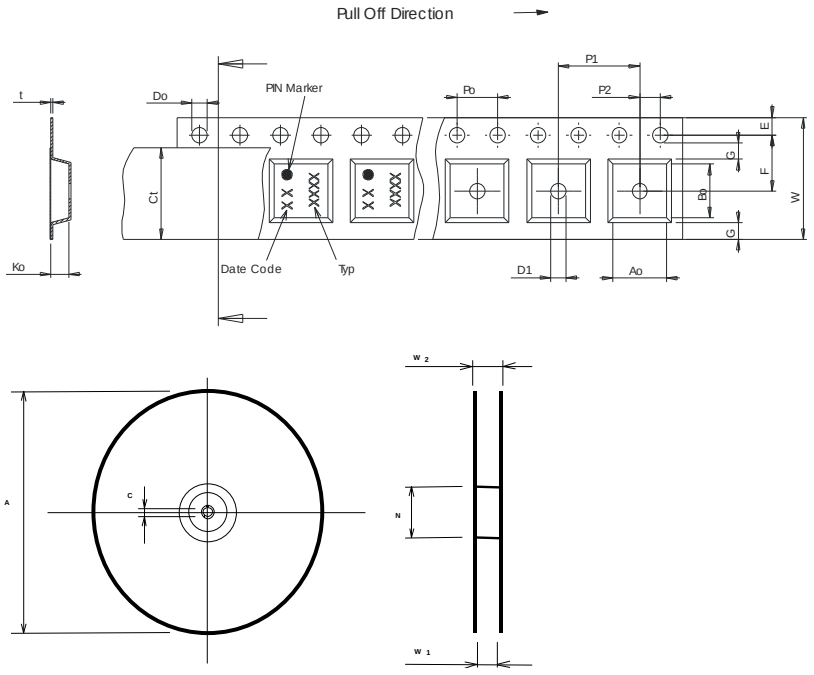
reel of empty components at start:	min. 300 mm
reel of empty components at start including leader:	min. 500 mm
trailer:	min. 300 mm

Tape (all dimensions in mm)

W	:	16.00	±0.3
Po	:	4.00	±0.1
Do	:	1.50	+0.1/-0
E	:	1.75	±0.10
F	:	7.50	±0.10
G(min)	:	0.60	
P2	:	2.00	±0.1
P1	:	12.00	±0.1
D1(min)	:	1.50	
Ao	:	7.60	±0.10
Bo	:	9.60	±0.10
Ct	:	13.30	
Ko	:	2.50	±0.10
t	:	0.30	±0.05

Reel (all dimensions in mm)

A	:330	or 180
W1	: 16.4	
W2(max)	: 22.40	
N(min)	: 50.00	
C	: 13.0	



The minimum bending radius is 45 mm.

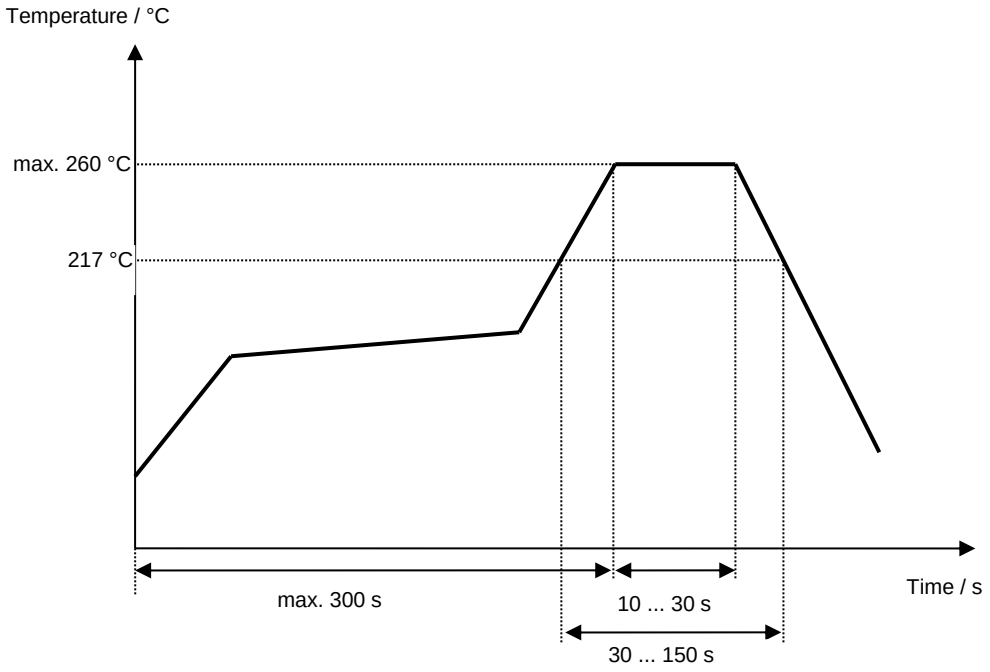
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Air reflow temperature conditions

Conditions	**Exposure**
Average ramp-up rate (30 °C to 217 °C)	less than 3 °C / second
> 100 °C	between 300 and 600 seconds
> 150 °C	between 240 and 500 seconds
> 217 °C	between 30 and 150 seconds
Peak temperature	max. 260 °C
Time within 5 °C of actual peak temperature	between 10 and 30 seconds
Cool-down rate (Peak to 50 °C)	less than 6 °C / second
Time from 30 °C to Peak temperature	no greater than 300 seconds

Chip-mount air reflow profile



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History

Version	Reason of changes	Name	Date
1.0	Generation of development specification	Bonnen	23.11.2017
1.1	Change passband and relative attenuation	Bonnen	07.12.2017
1.2	Generation of filter specification Changed typo in relative attenuation	Bonnen	23.08.2018

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